

.156" (3,96mm) POWER SOCKET FHP SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?FHP

Insulator Material: Black LCP

Contact Material: BeCu

Plating: Sn over 50µ" (1,27µm) Ni

Insertion Depth: (3,57mm) .140" to (8,76mm) .345" or pass-through from top

Wiping Distance: (0,38mm) .015"

Insertion Force: (Single contact only) 56oz (15,57N) avg.

Withdrawal Force: (Single contact only) 52oz (14,46N) avg.

RoHS Compliant: Yes

Processing: Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0,10mm) .004" max

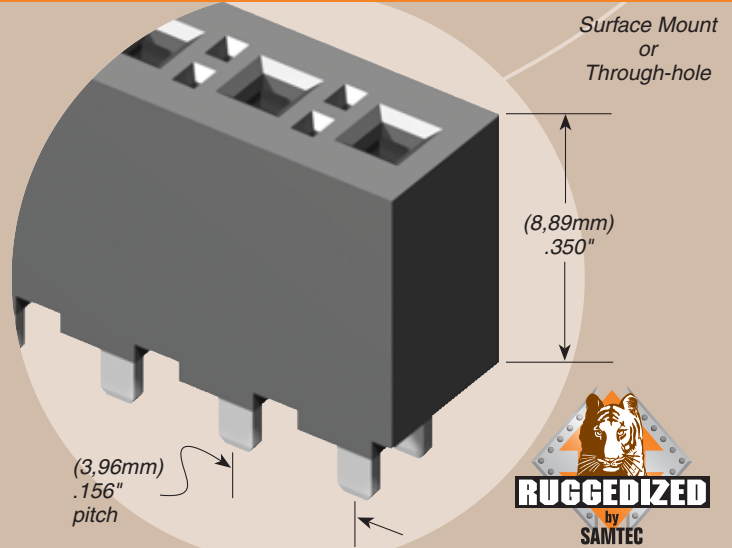


Mates with: FWJ, HFWJ, JW



CURRENT RATING		
AMBIENT TEMP	FHP/(H)FWJ	FHP/JW
20°C	14A	16.9A
40°C	12.2A	14.6A
60°C	10.1A	12.1A
75°C	8.2A	9.9A

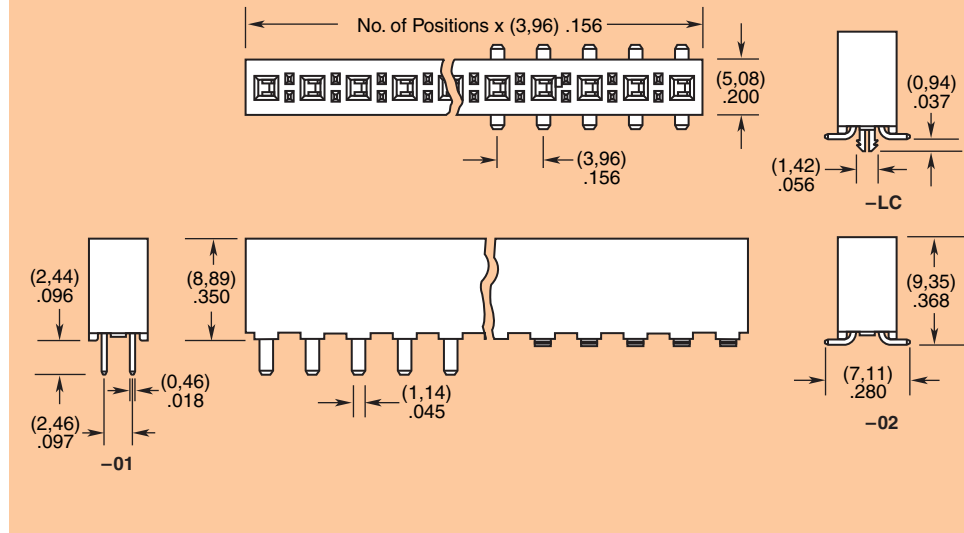
6 POSITIONS POWERED



APPLICATION SPECIFIC OPTION

Alignment pins available. Call Samtec.

FHP	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	S	OTHER OPTION
	02 thru 24	-01 = Through-hole -02 = Surface Mount	-T = Matte Tin		-LC = Locking Clip (-02 lead style only) -K = (6,50mm) .256" DIA Polyimide film Pick & Place Pad (-02 lead style only) -TR = Tape & Reel Packaging (Available on positions 2-24, 2-4 positions required in -TR) -02 lead style only



Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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